

ABSTRACT

5 A frame-shaped groove is formed on a panel adhering part
of a sealing board (10), a paste including low melting point
glass powder is buried in the groove, and a frame-shaped glass
paste layer is formed. A solvent included in the glass paste
layer is volatilized for solidification, and a low melting point
10 glass frame (22) is provided. Then, the low melting point glass
frame (22) protruded on the surface of the sealing board (10)
is removed, and the surface of a plane including the surface
of the adhering part of the sealing board (10) is flattened.
A low heat resistant layer (24) is formed on the flattened adhering
plane of the sealing board (10). The sealing board (10) is
15 arranged to face an element board (26) at a prescribed interval,
laser beams are applied on the low melting point glass frame
(22) through the element board (26), and the area is heated.
Thus, the low melting point glass rises, and the sealing board
(10) is welded with the element board.